http://icmm4.usacm.org

4th International Conference on Material Modeling

May 27th- 29th, 2015
Berkeley, California, USA

ICMM

USACM

Civil and Environmental Engineering
University of California, Berkeley

Mechanical Engineering
UNIVERSITY OF CALIFORNIA, BERKELEY

Registration and Fees

	Early registration	Late registration
Conference fee	$ 250	$ 300

The registration fee includes participation in all sessions, coffee breaks, a welcome reception (on Tuesday, May 26), and the conference banquet (on Thursday, May 28). Early registration before February 15, 2015 is advised.

Accommodation

There are a number of hotels in and around the Berkeley campus. The conference website provides direct links and contact information for these.

Abstracts

Abstracts should be written in plain text and submitted via the conference web-site. The deadline for submission of abstracts is January 15, 2015.

Important Dates

Abstract Submission Opens: November 1, 2014
Registration Opens: January 1, 2015
Abstract Submission Closes: January 15, 2015
Early Registration Closes: February 15, 2015
Paper Submission Closes: June 30, 2015

Scientific Committee

- Douglas Bammann, Mississippi State University, USA
- Frederic Barlat, Pohang University of Science and Technology, South Korea
- Albrecht Bertram, University of Magdeburg, Germany
- Francesco dell'Isola, Università di Roma La Sapienza, Italy
- Paweł Dłużewski, Institute of Fundamental Technological Research PAN, Poland
- Fionn Dunne, Imperial College London, UK
- Yuri Estrin, Monash University, Australia
- Samuel Forest, Mines ParisTech, France
- Marc Geers, Eindhoven University of Technology, The Netherlands
- Sanjay Govindjee, University of California, Berkeley, USA
- István Groma, Eötvös University, Hungary
- David McDowell, Georgia Institute of Technology, USA
- Karol Miller, University of Western Australia, Perth, Australia
- Nobutada Ohno, Nagoya University, Japan
- Roberto Paroni, University di Sassari, Italy
- Srinivasan M. Sivakumar, Indian Institute of Technology, Madras, India
- Arun Srinivasa, Texas A&M University, USA
- Bob Svendsen, RWTH Aachen University, Germany
- George Voyiadjis, Louisiana State University, USA
- Quan-Shui Zheng, Tsinghua University, PRC

Scientific Objectives

During the past decades, material modeling has become a field of central scientific importance. Although there exist many workshops, meetings, colloquia, *etc.* on specific materials and particular applications, here a single conference dedicated to material modeling with all its various facets is intended. To this end, the aim of the ICMM conference is to bring together researchers from the various fields of material modeling and material characterization and to cover essentially all aspects of material modeling. This will provide the opportunity for interaction between scientists working in different subareas of material mechanics who otherwise would not come into contact with each other.

This conference is the fourth in the ICMM series. The first ICMM took place in 2009 in Dortmund, Germany; the second in 2011 in Paris, France; the third in 2013 in Warsaw, Poland.

Venue

ICMM4 will take place on the campus of the University of California, Berkeley. The historic Berkeley campus, founded in 1868, is home to a rich and diverse intellectual community. Both on- and off-campus, there is a wide range of restaurants, cafés, bookstores and other interesting venues. Berkeley is only a short metro (BART) ride from downtown San Francisco, which is a premier tourist and cultural destination. Berkeley is also easily accessible by BART from the San Francisco International airport (the main international airport of the region) and the Oakland International Airport.

Main Topics

- Nonlinear elasticity and viscoelasticity
- Plasticity and viscoplasticity
- Strain gradient & nonclassical approaches
- Atomistic to continuum transitions
- Statistical mechanics
- Micro- and nano-scale modeling of hcp alloys
- Nanomechanics
- Phase-transforming materials
- Multiscale modeling
- Granular materials and particle systems
- Polymeric materials
- Biomaterials
- Electronic materials
- Multiferroic materials
- Creep, damage, fracture and fatigue
- Experimental identification and material characterization

Local Organizing Committee

Sanjay Govindjee, Co-chair
Panos Papadopoulos, Co-chair
Albrecht Bertram

Tentative Schedule

May 26: Registration & Welcome Party
May 27: Talks
May 28: Talks & Conference Banquet
May 29: Talks

Oral presentations of approximately 25 minutes including 5 minutes of discussion are planned.

Conference Proceedings

Submitted papers will be published after the conference as a special issue of a peer-reviewed international journal. Abstracts will be made available to all participants in electronic form.

Contact

For questions, please contact us at the following address:

ICMM4
Ruth Hengst, USACM Conference Coordinator
PO Box 8137
Austin, TX 78713
USA
Phone: +001-512-743-3273
http://icmm4.usacm.org
email: icmm4@usacm.org